PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
Yu-Jen Wang	05/08/2007
Denny Tang	05/08/2007
Hsu-Chen Cheng	05/08/2007

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Road 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code: 300-77		

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	11752157	

CORRESPONDENCE DATA

Fax Number: (214)200-0853

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 972-739-8660

Email: bonnie.boyle@haynesboone.com

Correspondent Name: Bonnie Boyle
Address Line 1: 901 Main Street
Address Line 2: Suite 3100

Address Line 4: Dallas, TEXAS 75202

ATTORNEY DOCKET NUMBER:	24061.896	
NAME OF SUBMITTER:	David M. O'Dell	

PATENT REEL: 019329 FRAME: 0207

500281810

± 840.00

___CH \$4

Total Attachments: 2

source=896Assignment#page1.tif source=896Assignment#page2.tif

PATENT REEL: 019329 FRAME: 0208

Docket No.: 2006-0704 / 24061.896

Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

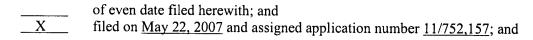
(1)	Yu-Jen Wang	of	8F, No. 213, Guandong Road Hsinchu City 300, Taiwan, R.O.C.
(2)	Denny Tang	of	153-13 F-2, 89th Alley, Guan-Fu Road, Sec. 1 Hsinchu City, Taiwan, R.O.C.
(3)	Hsu-Chen Cheng	of	3F, No. 11, Lane 260, Sec. 2, Chung-Hsin Road

have invented certain improvements in

SPIN TORQUE TRANSFER MRAM DEVICE

Hsinchu City 300, Taiwan, R.O.C.

for which we have executed an application for Letters Patent of the United States of America,



WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C., Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

PATENT REEL: 019329 FRAME: 0209

Docket No.: 2006-0704 / 24061.896

Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:

Yu-Jen Wang

Residence Address:

8F, No. 213, Guandong Road Hsinchu City 300, Taiwan, R.O.C.

Dated: 1007/May 108

Inventor Signature

Inventor Name:

Denny Tang

Residence Address:

153-13 F-2, 89th Alley, Guan-Fu Road, Sec. 1

Hsinchu City, Taiwan, R.O.C.

Dated: 2007 / May 108

Inventor Signature

Inventor Name:

Hsu-Chen Cheng

Residence Address:

3F, No. 11, Lane 260, Sec. 2, Chung-Hsin Road

Hsinchu City 300, Taiwan, R.O.C.

Dated:

Inventor Signature

R-896 - Assignment.doc

RECORDED: 05/22/2007

- 2 -

PATENT REEL: 019329 FRAME: 0210